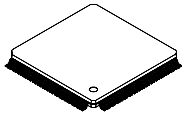
MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

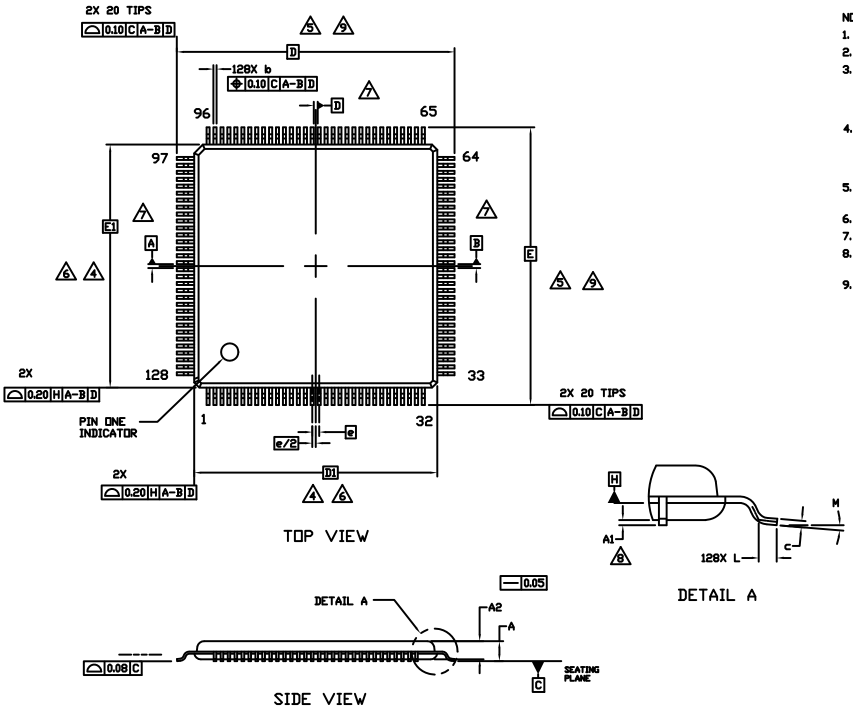


TQFP128 14x14 / TQFP128L

CASE 932BA

ISSUE A

DATE 30 APR 2015



TOP VIEW

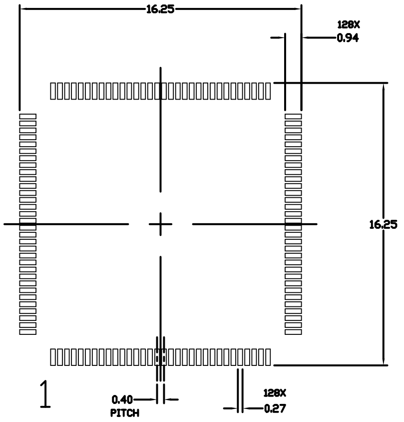
DETAIL A

SIDE VIEW

NOTES:

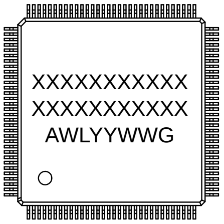
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b DOES NOT INCLUDE DAMBAR PROTRUSION. DAMBAR PROTRUSION SHALL BE 0.08 MAX. AT MMC. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT. MINIMUM SPACE BETWEEN PROTRUSION AND ADJACENT LEAD IS 0.07.
4. DIMENSIONS D1 AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.25 PER SIDE. DIMENSIONS D1 AND E1 ARE MAXIMUM PLASTIC BODY SIZE INCLUDING MOLD MISMATCH.
5. THE TOP PACKAGE BODY SIZE MAY BE SMALLER THAN THE BOTTOM PACKAGE SIZE BY AS MUCH AS 0.15.
6. DIMENSIONS D1 AND E1 TO BE DETERMINED AT DATUM PLANE H.
7. DATUMS A-B AND D ARE DETERMINED AT DATUM PLANE H.
8. A1 IS DEFINED AS THE VERTICAL DISTANCE FROM THE SEATING PLANE TO THE LOWEST POINT ON THE PACKAGE BODY.
9. DIMENSIONS D AND E TO BE DETERMINED AT DATUM PLANE C.

	MILLIMETERS	
DIM	MIN.	MAX.
A	---	1.20
A1	0.05	0.15
A2	1.00 REF	
b	0.13	0.23
c	0.09	0.20
D	16.00 BSC	
D1	14.00 BSC	
E	16.00 BSC	
E1	14.00 BSC	
e	0.40 BSC	
L	0.45	0.75
M	0°	7°



RECOMMENDED
MOUNTING FOOTPRINT

GENERIC MARKING DIAGRAM*



A = Assembly Location
WL = Wafer Lot
YY = Year
WW = Work Week
G = Pb−Free Package

*This information is generic. Please refer to device data sheet for actual part marking. Pb−Free indicator, “G” or microdot “ ▪”, may or may not be present.

ISSUE	**REVISION**	**DATE**
O	RELEASED FOR PRODUCTION FROM SANYO ENACT# S−508 TO ON SEMICONDUCTOR. REQ. BY D. TRUHITTE.	29 FEB 2012
A	REDREW DRAWING TO JEDEC STANDARDS. ADDED SOLDERING FOOTPRINT AND MARKING DIAGRAM. REQ. BY I. CAMBALIZA.	30 APR 2015

ON Semiconductor and ON are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. “Typical” parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including “Typicals” must be validated for each customer application by customer’s technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

© Semiconductor Components Industries, LLC, 2015